Refing Operating -50°C to + 100°C(Note 1) Storage -10°C to + 80°C(Note 3) Operating 40% to + 80%(Note 2) Storage 40% to + 80%(Note 3) Operating 40% to + 80%(Note 2) Storage 40% to + 80%(Note 3) Current AW0 28 to 24: 3A AW0 28 to 24: 3A AW0 28: 1A AW0 28: 1A Specifications Specifications Qurrent AW0 28: 1A AW0 28: 1A Construction Specifications Qurrent AW0 28: 1A (Note 4) Storage Construction X 2 X X 2 Construction Construction X 2 X X 2 Storage Practic Applications Some Applications X 2 X 2 Construction Some Applications Some Applications X 2 Storage Practic Applications Some Applications Some Applications X 2 Application Some Applications Some Applications X 2 Construction Some Applications Some Applications X 2 Constorage Applications<	Applicab	le sta	ndard										
Operang 40% to + 80%(Note 2) Storage 40% to + 70%(Note 3) Woltage 250% AC/DC Applicable connector DF3*552.C Current AWC 26 to 24 : 3A AWC 26 to 24 : 3A AWC 26 in 2A MWC 28 : 1A AWC 28 : 1A Current AWC 28 : 1A (Mcc 40, 28 : 2A Item Test method Requirements QT A Construction Test method Requirements QT A Construction Construction X 2 Construction Sol 00 PC Constructions X 2 Action Sol 00 PC Constructions X 2 Constructisstance Sol 00 A X					-55°C to + 105°C(Note 1)						-10°C to + 60°C(N	ote 3)	
Variation Contract DP3-V5-2/C Current AW0.37 to 24 : 30 A AV0.28 : 1.4 UL - CSA Voltage 307 ACDC Current AW0.28 : 1.4 AV0.28 : 1.4	temperature rar Operating			ge 🛆			-		ure range				
Ourrent AWG 22 to 24 : 3A AWG 26 : 2A AWG 26 : 1A UL - CSA rating Voltage AWG 26 : 3A AWG 26 : 1A SV ACDCC AWG 26 : 3A AWG 26 : 1A Image: Contract Contrac Contrat Contract Contract Contrat Contract Contract Contract Co							0	5			40% to + 70% (Note 3)		
Current ANY 22 B 2 A AVX 28 and AVX 2		Volta	age		250V AC/DC		Applica	able					
Current AWG 28 : 2A AWG 28 rating Current AWG 28 : A AWG 28					AWG 22 to 24 :	3A		SA	Voltage	e			
Image: construction Specifications Requirements OT A Construction According to drawing X		Curr	ent		AWG 26 :	2A			Curren	t			
Item Test method Requirements QT A Construction Visually and by measuring instrument. According to drawing. X > Barred examination Visually and by measuring instrument. According to drawing. X > Electric Characteristics Confirmed visually. Electric Characteristics X > Identical characteristics S00V DC. 1000M2 MIN. X > Vechanical operation 50 times insertions and extractions. 3) Contact resistance: 30m2 MAX. X > Vechanical operation 50 times insertions and extractions. 3) No flasheover or breakdown. X > Otharage, crack or tooseness of parts. 10 No damage, crack or tooseness of parts. X > Contact resistance: 30m2 MAX. 10. No damage, crack or tooseness of parts. X > Contact resistance: 30m2 MAX. 2. No damage, crack or tooseness of parts. X > Contact resistance: 30m2 MAX. 10. Contact resistance: 30m2 MAX. X - <td></td> <td>AWG 28 : 1A</td> <td>Note 4</td> <td>)</td>											AWG 28 : 1A	Note 4)
Construction Visually and by measuring instrument. According to drawing. X Y Electric Characteristics Continues visually. X 2 X 2 Electric Characteristics 20mV MAX. 1mA (DC or 1000H2). 30m(2 MAX. X - Mixed Level Method 20mV MAX. 1mA (DC or 1000H2). 30m(2 MAX. X - Visition resistance 500V DC. 1000M2 MIN. X - Visition resistance 500V DC. 1000M2 MIN. X - Visition Visition methods 10 No flashover or breakdown. X - Visition 20 for directoris 20 for directoris 20 for directoris X - Visition 76 mm, at h. for 3 directoris. 21 modenage, crack or losseness of parts. X - Environmental characteristics 20 modenage, crack or losseness of parts. X - 21 modenage, crack or losseness of parts. X - Environmental characteristics 20 modenage, crack or losseness of parts. X - 21 modenoresistrace is som? X -		tom				ecificati	ons			Poo	wiromonto		
Several examination Visuality and by measuing instrument. According to drawing. X Z <thz< th=""> Z <thz< th=""></thz<></thz<>					Test method					Req	luirements	QI	AI
tarking Confirmed visually. X Z X Z X Z X Z Z Z Z Z Z Z Z Z Z <td></td> <td></td> <td></td> <td>Visually an</td> <td>d by measuring instrument</td> <td></td> <td>Ac</td> <td>cordi</td> <td>na to dr</td> <td>awind</td> <td>n</td> <td>Y</td> <td>V</td>				Visually an	d by measuring instrument		Ac	cordi	na to dr	awind	n	Y	V
Electric characteristics 20mr MAX, 1mA (DC or 1000H2). 30mΩ MAX. X - Allival Level Method 30mΩ MAX. X - Insulation resistance 500V DC. 1000MΩ MIN. X - Valiage proof 650V AC for 1 min. No flashover or breakdown. X - Valiage proof 650V AC for 1 min. No flashover or breakdown. X - Valiage proof 650V AC for 1 min. No flashover or breakdown. X - Valiage proof 500 Imes insertions and extractions. ① Contact resistance: 30mΩ MAX. X - Valiage bange of the extracteristics Temperature 30min - 30min ① No damage, crack or losseness of parts. X - Stady state) Temperature - 50°C + 48°C ① Contact resistance: 30mΩ MAX. X - Stady state) Temperature - 50°C + 48°C ① Contact resistance: 30mΩ MAX. X - Stady state) Exposed at 40 ± 2 °C, 90 to 95 %, 96 h. ① Contact resistance: 500M2 MMX. X - Stady state) Number of reflow cycles : 2 cycles MAX. Declementation resistance: 500M2 MAX. X - Stady state)				, , ,				00101	ng to ai	aming	9.		X
Dentact Resistance insulation resistance 20m/V MAX, 1mA (DC or 1000Hz). 30mΩ MAX. X - Additive Level Wethod insulation resistance 500V DC. 1000MΩ MIN. X - Addition resistance 500V DC. 1000MΩ MIN. X - Additive Level Wethod 500V DC. 1000MΩ MIN. X - Addition resistance 500V DC. 1000MΩ MIN. X - Addition resistance 500 Thesistenets of parts. X - - Addition resistance 0. No flashover or breakdown. X - - Addition resistance 30mΩ MAX. X - 2 No damage, crack or losseness of parts. X - Addition resistance 30min - 30min - 2 No damage, crack or losseness of parts. X - Environmental characteristics Gractions. (1) Contact resistance: 30mΩ MAX. X - 2 Insulation resistance: 30mΩ MAX. X - 2 Insulation resistance: 30mΩ MAX. X	•	hars	actoristi									~	~
Allinoit Annual Allinoit </td <td></td> <td></td> <td></td> <td></td> <td>X 1mA (DC or 1000Hz)</td> <td></td> <td>30</td> <td>mO M</td> <td>ΙΔΧ</td> <td></td> <td></td> <td></td> <td></td>					X 1mA (DC or 1000Hz)		30	mO M	ΙΔΧ				
Instruction Instrument Inst								11122 10				^	
Mechanical characteristics Image: crack or losseness of parts. X - //bration 0.16 mes insertions and extractions. Image: crack or losseness of parts. X - //bration 0.76 mm, at 2 h, for 3 directions. Image: crack or losseness of parts. X - Shock 430 m/s ² duration of pulse 11 ms at 3 times for 3 Image: crack or losseness of parts. X - Shock 430 m/s ² duration of pulse 11 ms at 3 times for 3 Image: crack or losseness of parts. X - Environmental Inderacteristics Image: crack or losseness of parts. X - - Rajd change of the tawing the const memperature for 1 to 2h. Image: crack or losseness of parts. X - Jamp heat Exposed at 40 ± 2 * 0, 90 to 95 %, 96 h. Image: crack or losseness of parts. X - Stady state) Image: crack or losseness of parts. X - - - Stady state) Image: crack or losseness of parts. X - - - Stady state) Image: crack or losseness of parts. X - - -	Insulation resistance			500V DC.				1000 M Ω MIN .				Х	-
Mechanical operation 50 times insertions and extractions. ① Contact resistance: 30mf) MAX, X 1/bration Frequency 10 to 55 Hz, single amplitude ① No electrical discontinuity of 1µs. X 50 tox 400 m/s ² duration of pulse 11 ms at 3 times for 3 ① No electrical discontinuity of 1µs. X 50 tox 400 m/s ² duration of pulse 11 ms at 3 times for 3 ① No electrical discontinuity of 1µs. X 50 tox 400 m/s ² duration of pulse 11 ms at 3 times for 3 ① Contact resistance: 30mf) MAX. X 50 tox 10 no electrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X -	Voltage proof			650V AC for 1 min.				No flashover or breakdown.				Х	-
Mechanical operation 50 times insertions and extractions. ① Contact resistance: 30mf) MAX, X 1/bration Frequency 10 to 55 Hz, single amplitude ① No electrical discontinuity of 1µs. X 50 tox 400 m/s ² duration of pulse 11 ms at 3 times for 3 ① No electrical discontinuity of 1µs. X 50 tox 400 m/s ² duration of pulse 11 ms at 3 times for 3 ① No electrical discontinuity of 1µs. X 50 tox 400 m/s ² duration of pulse 11 ms at 3 times for 3 ① Contact resistance: 30mf) MAX. X 50 tox 10 no electrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X - 50 tox 10 molectrical discontinuity of 1µs. X -	Mechani	cal c	haracte	eristics			I						
/ibration Frequency 10 to 55 Hz; single amplitude ①. No electrical discontinuity of 1µs. X - 3hock 490 m/s ² duration of pulse 11 ms at 3 times for 3 directions. ①. No electrical discontinuity of 1µs. X - Shock 490 m/s ² duration of pulse 11 ms at 3 times for 3 directions. ①. No electrical discontinuity of 1µs. X - Environmental Characteristics 3 ○. No damage, crack or losseness of parts. X - Rapid change of emperature Temperature -55°C - +85°C ①. Contact resistance: 30mΩ MAX. X - 10 No damage, crack or losseness of parts. 3 No damage, crack or losseness of parts. X - 20 Insulation resistance: 30mΩ MAX. X - - 2 Insulation resistance: 30mΩ MAX. X - 21 Insulation resistance: 30mΩ MAX. X - - 2 Insulation resistance: 30mΩ MAX. X - 22 The start for to 25 % of the tank is 2 to 3 MIN) MAX - - 2 Insulation resistance: 30mΩ MAX. X - 23 Parts atelewing throm tomperature 150 to 180° C Perek temperature 250° C 10 sec. MAX.	Mechanical operation							~					-
0.75 mm. at 2 h, for 3 directions. (2) No damage, crack or looseness of parts. Shock 490 m/s ² duration of pulse 11 ms at 3 times for 3 (3) No electrical discontinuity of 1µs. X addirections. (2) No damage, crack or looseness of parts. X - Rapid change of emperature 55°C + +85°C (3) Contact resistance: 30mΩ MAX. X - Bamp heat Temperature 55°C + +85°C (3) Contact resistance: 30mΩ MAX. X - Bamp heat Exposed at 40 ± 2 °c, 90 to 95 %, 96 h. (3) Contact resistance: 500MΩ MIN. X - Steady state) (After leaving the room temperature for 1 to 2h.) (3) No damage, crack or looseness of parts. X - Steady state) (After leaving the room temperature for 1 to 2h.) (3) No damage, crack or looseness of parts. X - Steady state) (After leaving the room temperature for 1 to 2h.) (3) No damage, crack or looseness of parts. X - Steady state) (After leaving the room temperature state no store of excessive looseness of parts. (3) No damage, crack or looseness of parts. X - Steady state) (After leaving the room temperature state no loo'C (3) No damage, crack or looseness or parts. X - Steady state) (After refere to reflow cycles : 2 cycles MAX. (4) the terminals. (4)	Vibration			Frequency 10 to 55 Hz, single amplitude								x	_
directions. ② No damage, crack or losseness of parts. Environmental characteristics Sepid change of emperature Temperature -55°C + +85°C Time - 30min + 30min Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.) ① Contact resistance: 1000MΩ MIN. X - 3 No damage, crack or losseness of parts. (After leaving the room temperature for 1 to 2h.) ③ No damage, crack or losseness of parts. X - 3 No damage, crack or losseness of parts. (After leaving the room temperature for 1 to 2h.) ③ No damage, crack or losseness of parts. X - Steady state) - (After leaving the room temperature for 1 to 2h.) ③ No damage, crack or losseness of parts. X - Variation observations: Norder of reflow cycles : 2 cycles MAX. > ③ No damage, crack or losseness of parts. X - Soldering line at time : 90 to 120 sec. NAX. Pre-heat temperature : 230 °C A new uniform coating of solder shall cover soldering inco notact. X - Soldering time : 3s. Soldering time : 3s. Soldering time : 3s. - - - Soldering time : 3s. Soldering time : 3s. Soldering time : 3s. - - - <td colspan="3"></td> <td colspan="4">0.75 mm, at 2 h, for 3 directions.</td> <td colspan="4">② No damage, crack or looseness of parts.</td> <td></td> <td></td>				0.75 mm, at 2 h, for 3 directions.				② No damage, crack or looseness of parts.					
Environmental characteristics Rapid change of emperature Temperature -55°C→ +85°C (I) Contact resistance: 30mΩ MAX. Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.) Damp heat Steady state) Resistance to Number of reflow cycles : 2 cycles MAX. Duration above 230°C, 60 sec. MAX. Peak temperature: 250°C 10 sec. MAX. Duration above 230°C, 60 sec. MAX. Pre-heat temperature: 250°C 10 sec. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X = Soldering time : 3s. Not e1 : include the temperature rising by current. Note 3 :Apply to crimeing of not revisions Designed Checked 1 D1S-H-00001676 HT SATO Soldering time is applied for interim storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is app	Shock			-								X	-
emperature Tme 30min → 30min 20min → 30min	Environn	nenta	al chara	acteristi	CS				0,		·		
Under 5 Cycles. (The transferring time of the tank is 2 to 3 MIN) (After leaving the room temperature for 1 to 2h.) ③ No damage, crack or looseness of parts. Jamp heat Exposed at 40 ± 2 °c, 90 to 95 %, 96 h. ① Contact resistance: 30mΩ MAX. X - Steady state) ① No damage, crack or looseness of parts. ③ No damage, crack or looseness of parts. X - Steady state) ① Reflow soldering No deformation of case of excessive looseness of parts. X - Soldering heat ① Reflow soldering No deformation of case of excessive looseness of parts. X - Soldering heat ① Manual soldering No deformation of case of excessive looseness of parts. X - Soldering time attrene: 250°C 10 sec. MAX. Pre-heat temperature: 250°C 10 sec. No deformation of case of excessive looseness of parts. X - Soldering time is 3sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Soldering time :3se. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Soldering time :3se. No dation of long term storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is applied for interim stora	Rapid change of Tem				Femperature -55°C→ +85°C				(1) Contact resistance: $30m\Omega$ MAX.				—
(The transferring time of the tank is 2 to 3 MIN) (Alter leaving the room temperature for 1 to 2h.) ① Contact resistance: 30mΩ MAX. 2amp heat Steady state) Exposed at 40 ± 2 °c, 90 to 95 %, 96 h. ① Contact resistance: 30mΩ MAX. X 2 Insulation resistance: 30mQ MAX. ② Insulation resistance: 30mΩ MAX. X - 2 Insulation resistance: 1) Reflow soldering No deformation of case of excessive looseness of parts. X - Soldering heat 1) Reflow soldering No deformation of case of excessive looseness of parts. X - Pre-heat temperature: 520°C 10 sec. MAX. Pre-heat temperature: 520°C to 180°C. Pre-heat time : 90 to 120 sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Solderability Soldering time :3sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Aremarks Soldering time :3sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Vise 2.No condensing Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Stoe 4:Apply to crimping contact type. <td>temperature</td> <td>)</td> <td></td> <td colspan="4"></td> <td colspan="5">-</td> <td></td>	temperature)						-					
(After leaving the room temperature for 1 to 2h.) (1) Damp heat Exposed at 40 ± 2 °c, 90 to 95 %, 96 h. (1) Contact resistance: 300MΩ MN. (2) Insulation resistance: 500MΩ MN. Steady state) (2) Insulation resistance: 500MΩ MN. (3) No damage, crack or looseness of parts. (1) Resistance to 1) Reflow soldering No deformation of case of excessive looseness of parts. (1) Number of reflow cycles : 2 cycles MAX. Duration above 230°C, 60 sec. MAX. No deformation of case of excessive looseness of the terminals. (1) Peak temperature: :500 to 180°C. Pre-heat temperature: :500 to 180°C. (1) (1) (1) Soldering into temperature: :300°C, Soldering temperature: :300°C, Soldering into temperature: :300°C, (1) (1) Soldering temperature: :30°C A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - No tef 1: Include the temperature rising by current. (2) (2) A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - No tef 1: Include the temperature rising by current. (2) (2) (2) (2) (2) Note 1: Include the tempera						to 3 MIN)	3	No d	lamage,	crack	or looseness of parts.		
Damp heat Steady state) Exposed at 40 ± 2 °c, 90 to 95 %, 96 h. ① Contact resistance: 300MΩ MAX. X - Steady state) ① Reflow soldering ③ No damage, crack or looseness of parts. X - Soldering heat 1) Reflow soldering No deformation of case of excessive looseness of the terminals. X - Duration above 230°C, Pre-heat time : 90 to 120 sec. 2.) Manual soldering time : 3sec. No deformation of case of solder shall cover minimum of 95 % of the surface being immersed. X - Soldering time : 3se. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Soldering time : 3se. No deformation of for the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. X - Approved K1. AK1YAMA 15. 12. 1 Designed Checked Date 1 D1S-H-00001676 HT. SAT0 TS. FUKUSHIMA 15. 12. 1 Inless otherwise specified, refer to IEC 60512. Drawing no. ELC-367269-51-00 Unless otherwise specified, refer to IEC 60512. Drawing no. ELC-367269-51-00 Unless otherwise specification T					÷								
Resistance to Soldering heat 1) Reflow soldering Number of reflow cycles : 2 cycles MAX. Duration above 230°C, 60 sec. MAX. Pre-heat temperature: 250°C 10 sec. MAX. Pre-heat temperature: 150°C to 180°C Pre-heat temperature: 30°C, Soldering iron temperature: 300°C, Soldering iron temperature: 300°C, Soldering time : 3sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Solderability Soldering temperature: 200 °C Soldering time : 3s. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time : 3s. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time : 3s. Besting time : 3s. Cont A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Ts. FUKUSHIMA 16. 05. 2 Image: Count Description of revisions Designed Checked Date Image: Soldering termer type. Image: Soldering termer trains to a solder the surface being immersed. Image: Soldering termerature is a solder to the surface being immersed. Image: Soldering termerature is a solder to the surface being immersed	Damp heat							① Contact resistance: $30m\Omega$ MAX.					-
Resistance to Soldering heat 1) Reflow soldering Number of reflow cycles : 2 cycles MAX. Duration above 230°C, 60 sec. MAX. Peak temperature : 250°C 10 sec. MAX. Pre-heat temperature : 250°C 10 sec. MAX. Pre-heat temperature : 250°C 10 sec. No deformation of case of excessive looseness of the terminals. X - Soldering heat Number of reflow cycles : 2 cycles MAX. Pre-heat temperature : 250°C 10 sec. MAX. Pre-heat temperature : 250°C 10 sec. No deformation of case of excessive looseness of the terminals. X - Soldering time : 30 to 120 sec. 2) Manual soldering Soldering time is esc. No strength on contact. No strength on contact. X - Soldering time : 3s. Soldering time : 3s. Soldering time : 3s. Y - Remarks Soldering time : 3s. Soldering time : 3s. Y - Note 1: Include the temperature rising by current. Wote 2:No condensing Solder for interim storage during transportation. A new uniform coating temperature and humidity range is applied for interim storage during transportation. Approved K1. AK1YAMA 15. 12. 1 I D1S-H-00001676 HT. SATO TS. FUKUSHIMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1 I D1S-H-00001676 HT. SATO TS. FUKUSHIMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1	(Steady stat	te)						-					
Soldering heat Number of reflow cycles : 2 cycles MAX. Duration above 230°C, 60 sec. MAX. Pre-heat temperature: 150° to 180°C Pre-heat temperature: 150° to 180°C Pre-heat temperature: 100°C, Soldering irme : 3sec. of the terminals. X Soldering irme: 380°C, Soldering irme: 380°C, Soldering time: 380°C,	Desisteres	4					-	- 0					_
Duration above 230°C, 60 sec. MAX. Peak temperature: 250°C 10 sec. MAX. Pre-heat temperature: 150 to 180°C Pre-heat temperature: 300°C, Soldering time : 3sec. No strength on contact. Soldering temperature: 230°C No strength on contact. No strength on contact. Soldering temperature: 230°C No strength on contact. Soldering temperature: 230°C A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X Count Description of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4: Apply to crimping contact type. Count Description of revisions Designed Checked Date 1 DIS-H-00001676 HT. SAT0 TS. FUKUSHIMA 16. 05. 2 Jnless otherwise specified, refer to IEC 60512. Drawing no. ELC-36				,	0	IAX.	-					X	_
Pre-heat time : 150 to 180°C Pre-heat time : 90 to 120 sec. 2) Manual soldering Soldering time : 38c. Image: Constant in the image: Soldering time : 300°C, Soldering time : 38c. Solderability Soldering time : 38c. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X Soldering time : 38. Soldering time : 38c. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Soldering time : 38. Soldering time : 38c. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time : 38. Soldering time : 38c. - - Note 1: Include the temperature rising by current. Note 2:No condensing Soldering term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to crimping contact type. - Count Description of revisions Designed Checked Date 1 DIS-H-00001676 HT. SAT0 TS. FUKUSHIMA 15. 12. 1 Inless otherwise specified, refer to IEC 60512. Drawing no. ELC-367269-51-00 Joness otherwise specified, refer to IEC 60512. Drawing no. ELC-367269-51-00	Coldening In	Jui											
Pre-heat time : 90 to 120 sec. 2) Manual soldering Soldering iron temperature :300°C, Soldering time : 3sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. Soldering time :3s. Monual soldering time :3s. Remarks Soldering time :3s. Vate 1: Include the temperature rising by current. Note 2:No condensing Vate 2:No condensing Vate for interim storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to crimping contact type. Implementation Description of revisions Designed Checked Date Approved K1. AKIYAMA 15. 12. 1 Indees otherwise specified, refer to IEC 60512. Drawing no. ELC-367269-51-0U Indee QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-0U Indee QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-0U Image Selecification sheet													
2) Manual soldering Soldering iron temperature :300°C, Soldering time : 3se. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Soldering time : 3se. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time : 3se. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time : 3se. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Note 1: Include the temperature rising by current. Note 2:No condensing Note 2:No condensing Note 1: Include the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4: Apply to crimping contact type. Note 4: Apply to crimping contact type. Image: Apply to crimping contact type. Image: Approved KI. AKIYAMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1 Designed HT. SATO 15. 12. 1 Drawn MI. SAKIMURA 15. 12. 1 Drawn MI. SAKIMURA				Pre-heat time : 90 to 120 sec.									
Soldering time : 3sec. No strength on contact. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time : 3s. A new uniform coating of solder shall cover Soldering time : 3s. X - Remarks Note 1: Include the temperature rising by current. Soldering time : 3s. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Note 2: No condensing Note 3: Apply to the condition of long term storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is applied for interim storage during transportation. Note 4: Apply to crimping contact type. Image: the 1 model of the exception of revisions Designed Checked Date Image: the 1 model of the exception of revisions Designed K1. AK1YAMA 16. 05. 2 Image: the 2 model of the exception of revisions Designed HI. SATO TS. FUKUSHIMA 15. 12. 1 Image: the 2 model of the exception of revisions Designed HI. SATO 15. 12. 1 Designed HI. SATO 15. 12. 1 Image: the 2 model of the exception of th													
No strength on contact. A new uniform coating of solder shall cover Soldering time :3s. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time :3s. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time :3s. A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Soldering time :3s. Soldering time :3s. - - Note 1: Include the temperature rising by current. Soldering time storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to crimping contact type. - Not 4: Apply to crimping contact type. I Dis-H-00001676 HT. SATO TS. FUKUSHIMA 16.05.2 Inless otherwise specified, refer to IEC 60512. Image: Disigned HT. SATO TS. FUKUSHIMA 15.12.1 Inless otherwise specified, refer to IEC 60512. Drawing no. ELC-367269-51-00 Image: Disigned HT. SATO 15.12.1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00													
Solderability Soldering temperature :230 °C A new uniform coating of solder shall cover minimum of 95 % of the surface being immersed. X - Remarks Note 1: Include the temperature rising by current. Note 2:No condensing Note condition of long term storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to the condition of long term storage during transportation. Note 4:Apply to crimping contact type. Count Description of revisions Designed Checked Date 1 D1S-H-00001676 HT. SAT0 TS. FUKUSHIMA 16.05.2 Jnless otherwise specified, refer to IEC 60512. Mark MURA 15.12.1 Drawin MI. SAKIMURA 15.12.1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 ELC-367269-51-00 MES Specification sheet Part no. DF3EA-*P-2H (51) Mark 1/2 Mark 1/2					0								
Soldering time :3s. minimum of 95 % of the surface being immersed. Remarks Note 1: Include the temperature rising by current. Note 2:No condensing Note 3: Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4: Apply to crimping contact type. Count Description of revisions Designed Checked Date 1 DIS-H-00001676 HT. SAT0 TS. FUKUSHIMA 16.05.2 Juless otherwise specified, refer to IEC 60512. Approved K1. AKIYAMA 15.12.1 Designed HT. SAT0 TS. FUKUSHIMA 15.12.1 Designed HT. SAT0 15.12.1 Designed HT. SAT0 15.12.1 Ote QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 Mote QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543 Δ 1/	Solderability	/						A new uniform coating of solder shall cover X					+
Note 1: Include the temperature rising by current. Note 2:No condensing Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to crimping contact type. Count Description of revisions Designed Checked Date Approved K1. AKIYAMA 16. 05. 2 Approved K1. AKIYAMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1 Designed HT. SATO TS. FUKUSHIMA 15. 12. 1 Designed HT. SATO 15. 12. 1 Designed HT. SATO 15. 12. 1 Juless otherwise specified, refer to IEC 60512. Drawn MI. SAKIMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 MSS Specification sheet Part no. DF3EA-*P-2H (51) Image: Part no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543 M 1/2	-			5				minimum of 95 % of the surface being immersed.					
Note 2:No condensing Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board, operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to crimping contact type. Designed Checked Date Count Description of revisions Designed Checked Date 1 DIS-H-00001676 HT. SAT0 TS. FUKUSHIMA 16. 05. 2 Approved KI. AKIYAMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1 Juless otherwise specified, refer to IEC 60512. Drawin MI. SAKIMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 MSS Specification sheet Part no. DF3EA-*P-2H (51) March Hirose electric co., Itd. Code no. CL543 A 1/*	Remarks	ide the	tomporot	Iro ricina -									
Note 3:Apply to the condition of long term storage for unused products before pcb on board, after pcb board , operating temperature and humidity range is applied for interim storage during transportation. Note 4:Apply to crimping contact type. Designed Checked Date 1 DIS-H-00001676 HT. SAT0 TS. FUKUSHIMA 16. 05. 2 Approved KI. AKIYAMA 15. 12. 1 Designed HT. SAT0 TS. FUKUSHIMA 15. 12. 1 Juless otherwise specified, refer to IEC 60512. Drawn MI. SAKIMURA 15. 12. 1 Drawing no. ELC-367269-51-00 Images Specification sheet Part no. DF3EA-*P-2H (51) Images Images Images Mages 1/2			•	ine rising b	y current.								
Count Description of revisions Designed Checked Date 1 DIS-H-00001676 HT. SAT0 TS. FUKUSHIMA 16. 05. 2 Approved KI. AKIYAMA 15. 12. 1 Checked TS. FUKUSHIMA 16. 05. 2 Approved KI. AKIYAMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1 Designed HT. SAT0 15. 12. 1 Designed HT. SAKIMURA 15. 12. 1 Drawing no. ELC-367269-51-00 Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., Itd.<			0	of long ter	m storage for unused produc	cts before pc	b on boar	rd, aft	er pcb b	oard ,	, operating temperature an	d	
Count Description of revisions Designed Checked Date 1 D1S-H-00001676 HT. SAT0 TS. FUKUSH1MA 16. 05. 2 Approved K1. AK1YAMA 15. 12. 1 Checked TS. FUKUSH1MA 15. 12. 1 Designed HT. SAT0 15. 12. 1 Drawn MI. SAKIMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 FIFS Specification sheet Part no. DF3EA-*P-2H (51) Introse electric co., Itd. Code no. CL543 <u>A</u> 1/2		-	• • •		erim storage during transport	ation.							
1 DIS-H-00001676 HT. SATO TS. FUKUSHIMA 16. 05. 2 Approved KI. AKIYAMA 15. 12. 1 Checked TS. FUKUSHIMA 15. 12. 1 Jnless otherwise specified, refer to IEC 60512. Designed HT. SATO 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 KFS Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543 A 1/2	Note 4:Apply	to crir	nping cont	act type.									
Approved K1. AKTYAMA 15. 12. 1 Checked TS. FUKUSHTMA 15. 12. 1 Designed HT. SATO 15. 12. 1 Designed HT. SATO 15. 12. 1 Drawn MI. SAKTMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 MSS Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543 A 1/2	Cour	nt		Descript	on of revisions		Designed	d			Checked	D	ate
Checked TS. FUKUSHIMA 15. 12. 1 Designed HT. SATO 15. 12. 1 Designed HT. SATO 15. 12. 1 Drawn MI. SAKIMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 FRS Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543	1			DIS-	H-00001676		HT. SATO)	TS. FUKUSHIMA		TS. FUKUSHIMA	16.	05. <u>2</u> 6
Designed HT. SAT0 15. 12. 1 Jnless otherwise specified, refer to IEC 60512. Drawn MI. SAKIMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 FRS Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543 Δ 1/2									Approved		KI.AKIYAMA	15.	12. 17
Jnless otherwise specified, refer to IEC 60512. Drawn M1. SAKIMURA 15. 12. 1 Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 MRS Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., Itd. Code no. CL543									Check	ked	TS. FUKUSHIMA	15.	12.17
Note QT:Qualification Test AT:Assurance Test X:Applicable Test Drawing no. ELC-367269-51-00 MRS Specification sheet Part no. DF3EA-*P-2H (51) Hirose electric co., ltd. Code no. CL543 A 1/2									Desig	ned	HT. SATO	15.	12. 17
Specification sheet Part no. DF3EA-*P-2H(51) Hirose electric co., ltd. Code no. CL543 <u>A</u> 1/2	Unless othe	rwise	specified,	refer to IE	EC 60512.			Drawn		vn	MI. SAKIMURA	MI. SAKIMURA 15.1	
Hirose electric co., ltd. Code no. CL543 A 1/2	Note QT:Qualification Test AT:As				surance Test X:Applicable 1	Dra	Drawing no.			ELC-367269-51-00			
Hirose electric co., ltd. Code no. CL543 A 1/2	າມາ			Sneci	fication sheet		Part no	no.			DF3EA-*P-2H(51)		
	СЛ											٨	1/1
ORM HD0011_9_1				111030			Code no	υ.			01040		1/1

FORM HD0011-2-1